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FLUX FOR DIP SOLDERING

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FLUX FOR DIP SOLDERING

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Known solder fluxes cannot be used for dip soldering, due to their low boiling temperatures.

The essence of this invention consists of the fact that in order to increase flux activity and fluidity at 160 to 140°C and to prevent corrosion of solder joints, flux components are selected in the following percentage ratio: glycerin 95 to 97, diethylamine hydrochloride 5 to 3.

The flux described is intended for soldering of copper, copper alloys and other metals covered with nickel, zinc and silver. Soldering with this flux is done with tin-zinc and tin-lead solders with a melting temperature of 130 to 200°C.

The basic component of the flux is the high-boiling liquid, glycerin (boiling point, 290°C), hence, soldering may be performed by dipping.

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Purpose of Invention

Flux for the dip-solder method containing glycerin and diethylamine hydrochloride is distinguished by the fact that, in order to increase flux activity and fluidity at 160 to 240°C, and to increase the corrosion resistance of solder fusions, the flux components are taken in the following percentage ratio: glycerin 95 to 97, diethylamine hydrochloride 5 to 3.